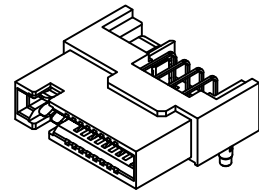
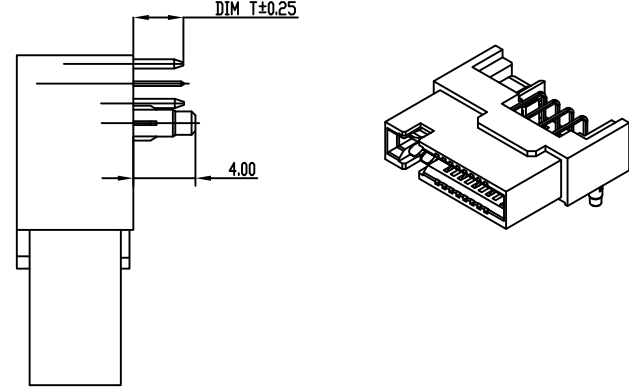
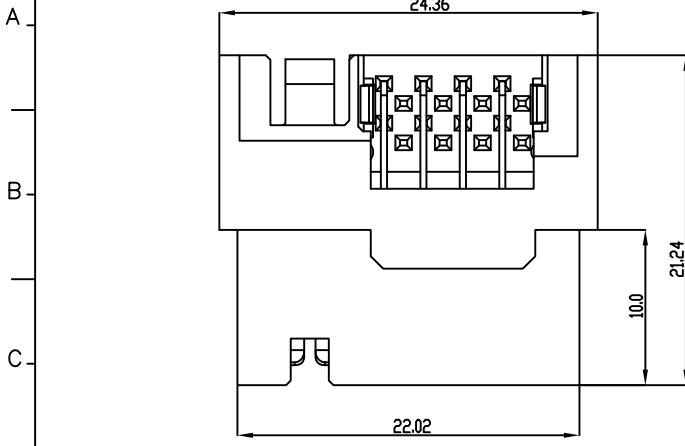
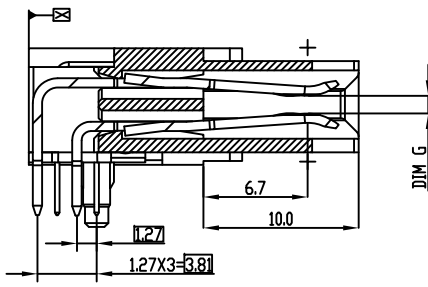
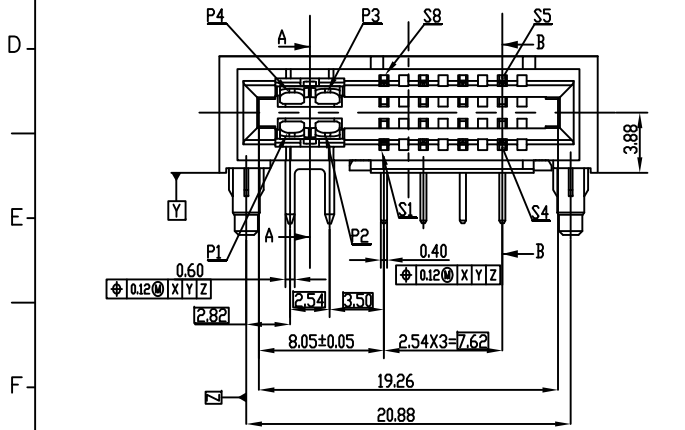


REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN170730	

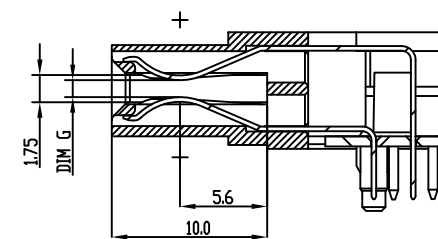


Material and Plating:
Housing: LCP, UL94V-0, BLACK.
Power Contacts: High Conductivity Copper .
30u" Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .
Signal Contacts: Phosphor Bronze .
30u" Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .

Electrical Characteristics:
Current Rating: Power Pin 12.5A(UL) .
Signal Pin 1.5A .
Dielectric Withstanding Voltage:
Power Pin DC 1000V For 1 Minute.
Signal Pin DC 500V For 1 Minute.
Contact Resistance: Power Pin 0.6mΩ max.
Signal Pin 25mΩ max.
Insulation Resistance: Power Pin 5000MΩ min.at DC 500V.
Signal Pin 500MΩ min.at DC 500V.
Operating Temperature: -55°C~+105°C.
*Rohs Compliant



Section: A-A



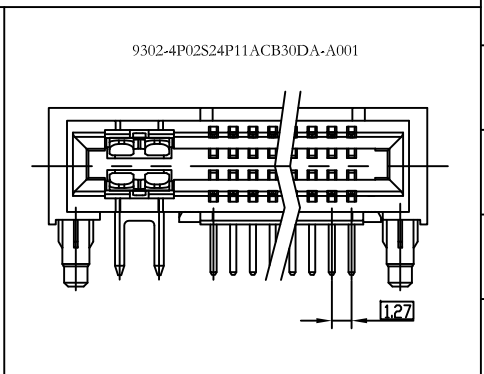
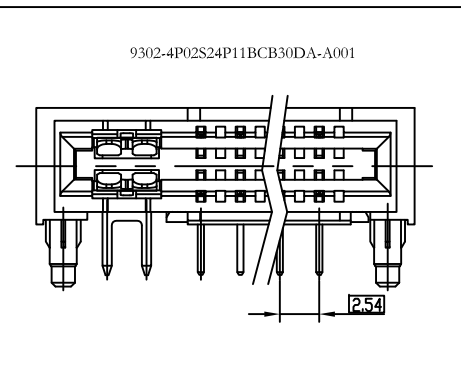
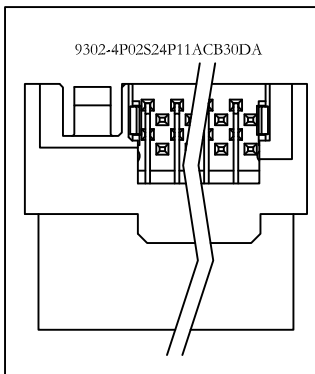
Section: B-B

Note:
Single Ended:
Insertion Loss:-3dB@1.5625GHz
Return Loss:-5dB@1.5625GHz
NEXT Crosstalk:<-25dB to 1.5625GHz
Differential:
Insertion Loss:-3dB@3.125GHz
Return Loss:-5dB@3.125GHz
NEXT Crosstalk:<-30dB to 3.125GHz

9302- 4 P02 S16 P 1 1 B CB 30 D A -A001
Series
4:Female Right-angle
PXX:Power Pin(00~20)
SXX:Signal Pin(00~80)
N:W/O Post
P:With Post=4.00mm
B:With Post=3.40mm
1: DIM T=3.25mm
2: DIM T=2.60mm
Internal Code
A:Tray Package
D: Dip Type
30: 30 u"
CB: Contact Au+Pd/Ni,Dip Tin
C: Selective Gold Plated
G: Gold Plated
B : Signal Pitch 2.54
A : Signal Pitch 1.27
See Fig.1
See Fig.2

1: DIM G(GAP)1.10mm
2: DIM G(GAP)1.80mm

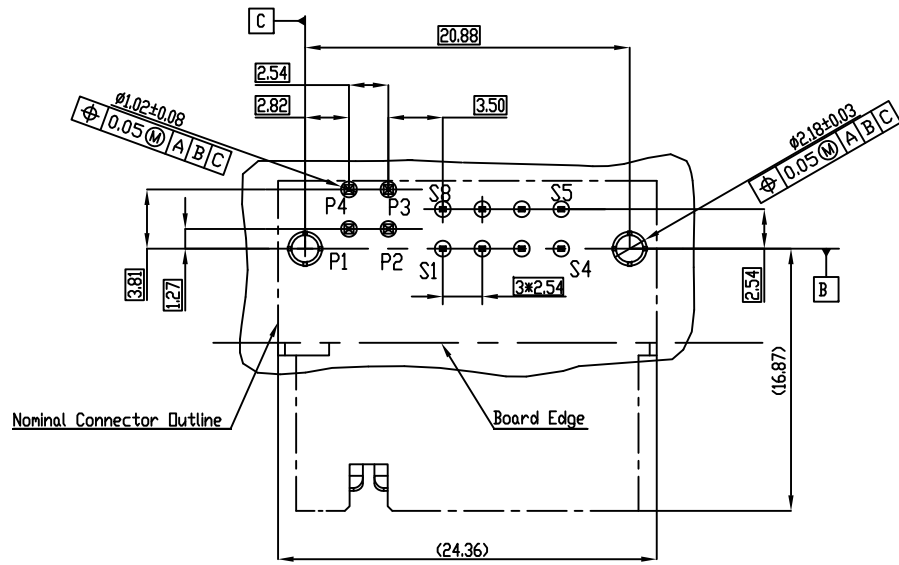
Table A



Tolerances	Dwg.No.	9302-D0000-001		Title:
X=±0.5	Projection			9302 Series High Power Card Edge
.X=±0.25	Unit	mm	Scale 1:1	
.XX=±0.15	Drawn By	WP 07/19'17		

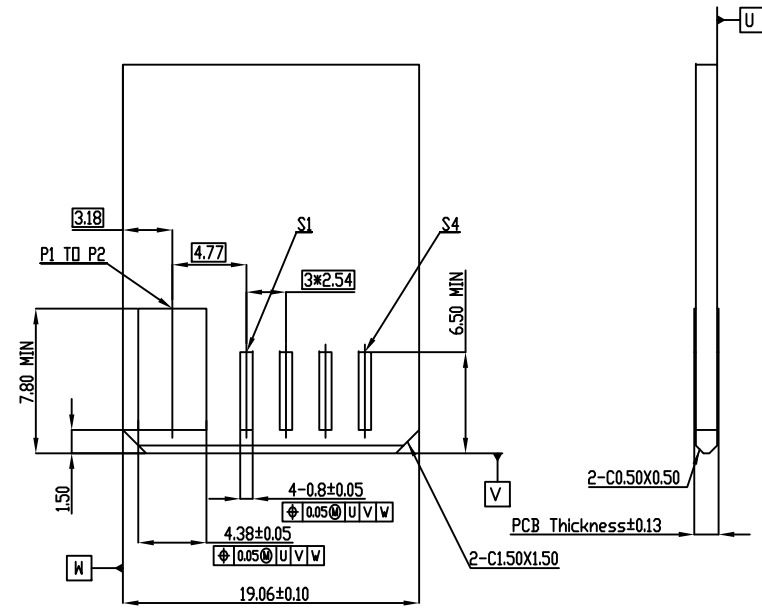
OUPIN			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 9302-4P02S16P11BCB30DA-A001			
SHEET	1/3	Ver.No.	R1

REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN170730	



P.C.B Layout
(Tolerance: ± 0.05)

Fig.1



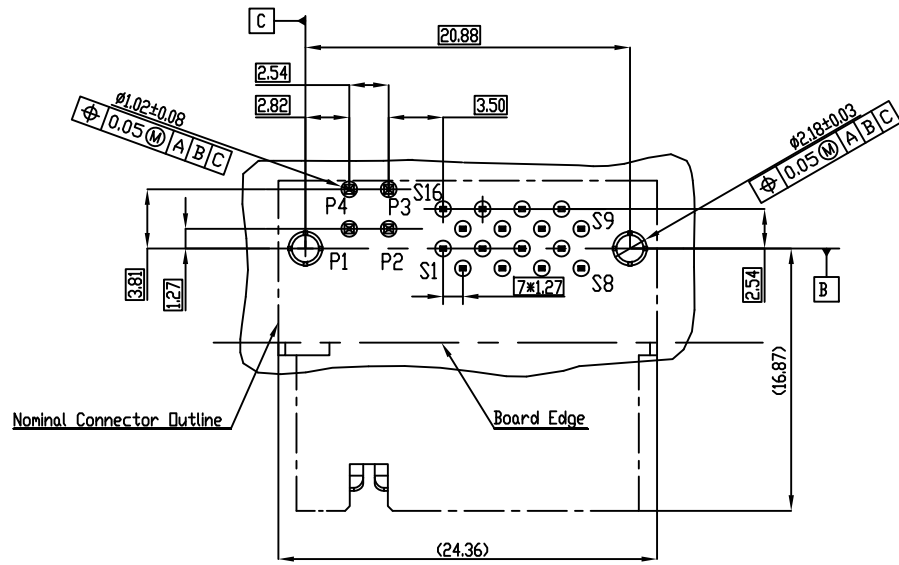
RECOMMENDED MATING BOARD
FOOT PRINT

Table A	
Dim G	PCB Thickness
1.10	1.57
1.80	2.30

Tolerances	Dwg.No.	9302-D0000-001		Title:	
X = ± 0.5	Projection			9302 Series High Power Card Edge	
.X = ± 0.25	Unit	mm	Scale		1:1
.XX = ± 0.15	Drawn By	WP 07/19'17			

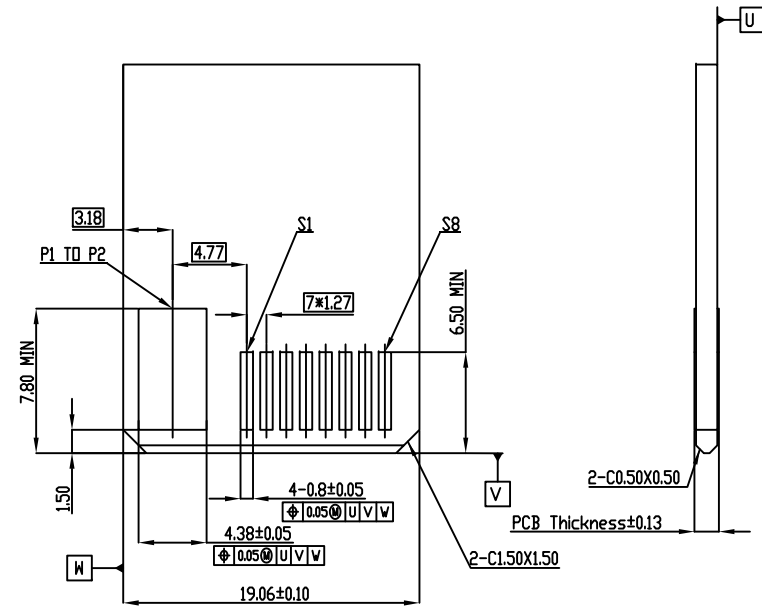
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N:9302-4P02S16P11BCB30DA-A001			
SHEET	2/3	Ver.No.	R1

REV.	SPECIFICATION	ECN NO.	APPD.
R1		ECN170730	


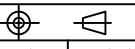


P.C.B Layout
(Tolerance: ± 0.05)

Fig.2



RECOMMENDED MATING BOARD
FOOT PRINT

Tolerances	Dwg.No.	9302-D0000-001	Title:		 OUPIIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 9302-4P02S16P11BCB30DA-A001 SHEET 3/3 Ver.No. R1
X = ± 0.5	Projection		9302 Series High Power Card Edge		
.X = ± 0.25	Unit	mm	Scale	1:1	
.XX = ± 0.15	Drawn By	WP 07/19'17			